

- Crystal Unit for Audio-Visual, Office Equipment
- Ultra-miniature and low profile. (2.5x2.0x0.45mm)
- · Ceramic package.
- A lead free product.
- Reflow compatible.

Applications

- Digital electronics
- Audio Visual, Office equipment

Standard Frequencies (kHz)

	(KIIZ)
27000.000	
27120.000	
30000.000	
32000.000	
33000.000	
33333.000	
40000.000	
48000.000	
54000.000	

^{*} Please inquire about frequencies other than the above.

Specifications

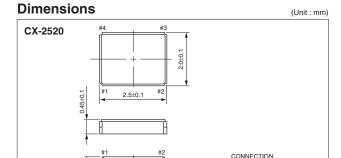
Items	Symbol	Specification	Units	Remarks
Frequency Range	Fo	26000~60000	kHz	
Overtone Order		Fundamental		
Frequency Tolerance	ΔF/F	±50	ppm	@ 25°C
Frequency Temperature Characteristics	ΔF/T	±50	ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	CI	Table 1	ohm	
Level of Drive		Table 2	μW	
Load Capacitance	C∟	8	pF	
Operating Temp. Range	Topr	-10~+70	°C	
Storage Temp. Range	Тѕтс	-40 ~ +85	°C	

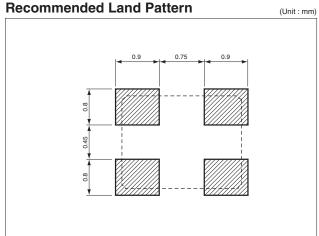
^{*} Please inqurie about specifications other than the above.

Table1 Motional Series Resistances

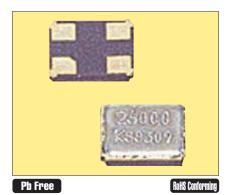
Frequency Range	Units		
26000~34999kHz	100	ohm	
35000~60000kHz	50	ohm	

Frequency Range	Level of Drive	Units
26000~60000kHz	10(100 max.)	μW









- Reference frequency for telecommunication systems
- Reflow compatible
- Using Ceramic Package resulting in high reliability
- Small and low profile

Applications

• Mobile communications, Bluetooth, Wireless LAN

Standard Frequencies (kHz)

	(KI 12)
26000.000	
27120.000	
32000.000	
38400.000	
40000.000	
44000.000	

^{*} Please inquire about frequencies other than the above.

Specifications

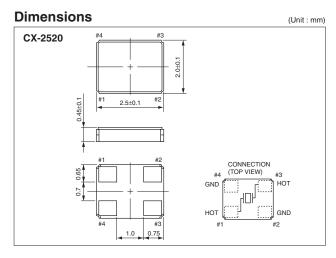
Items	Symbol	Specification	Units	Remarks
Frequency Range	Fo	26000~60000	kHz	
Overtone Order		Fundamental		
Frequency Tolerance	ΔF/F	±10	ppm	@ 25°C
Frequency Temperature Characteristics	ΔF/T	±15	ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	CI	Table 1	ohm	
Level of Drive		Table 2	μW	
Load Capacitance	C∟	8	pF	
Operating Temp. Range	Topr	-30~+85	°C	
Storage Temp. Range	Тѕтс	-40~+85	°C	

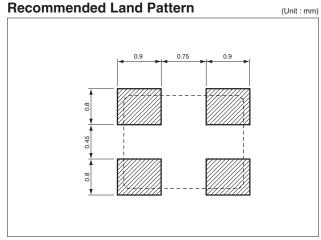
^{*} Please inqurie about specifications other than the above.

Table1 Motional Series Resistances

Frequency Range	Motional Series Resistance	Units	
26000~34999kHz	100	ohm	
35000~60000kHz	50		

Frequency Range	Level of Drive	Units
26000~60000kHz	10(100 max.)	μW









- Crystal Unit for Audio-Nisual, Office Equipment.
- Miniature and low profile (3.2x2.5x0.6mm)
- Ceramic package.

for Audio & Visual, Office Equipment

- · A lead free product.
- Reflow compatible.

Applications

- Digital electronics
- Audio Visual, Office equipment

Standard Frequencies

12000.000	25000.000
13560.000	26000.000
14318.180	27000.000
14745.600	27120.000
16000.000	30000.000
18432.000	33000.000
20000.000	33333.000
22579.200	40000.000
24000.000	48000.000
24576.000	54000.000

^{*} Please inquire about frequencies other than the above.

Specifications

Items	Symbol	Specification	Units	Remarks
Frequency Range	Fo	12000~54000	kHz	
Overtone Order		Fundamental		
Frequency Tolerance	ΔF/F	±50	ppm	@ 25°C
Frequency Temperature Characteristics	ΔF/T	±50	ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	CI	Table 1	ohm	
Level of Drive		Table 2	μW	
Load Capacitance	C∟	8	pF	
Operating Temp. Range	Topr	-10~+70	°C	
Storage Temp. Range	Тѕтс	-40~+85	°C	

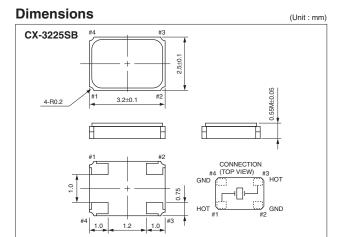
^{*} Please inqurie about specifications other than the above.

Table1 Motional Series Resistances

Frequency Range	Motional Series Resistance	Units
12000~13999kHz	300	
14000~15999kHz	200	- h
16000~26999kHz	100	ohm
27000~54000kHz	50	

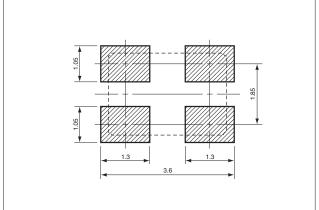
Table2 Level of Drive

Frequency Range	Level of Drive	Units
12000~54000kHz	10(100 max.)	μW



Recommended Land Pattern

(Unit:mm)









- Reference frequency for telecommunication systems
- Reflow compatible
- Using Ceramic Package resulting in high reliability
- Small and low profile

Applications

• Mobile communications, Bluetooth, Wireless LAN

Standard Frequencies (kHz)

12000.000	26000.000
13000.000	27120.000
13560.000	32000.000
15360.000	38400.000
16000.000	40000.000
19200.000	44000.000
20000.000	

^{*} Please inquire about frequencies other than the above.

Specifications

Items	Symbol	Specification	Units	Remarks
Frequency Range	Fo	12000~54000	kHz	
Overtone Order		Fundamental		
Frequency Tolerance	ΔF/F	±10	ppm	@ 25°C
Frequency Temperature Characteristics	ΔF/T	±15	ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	CI	Table 1	ohm	
Level of Drive		Table 2	μW	
Load Capacitance	C∟	8	pF	
Operating Temp. Range	Topr	-30~+85	°C	
Storage Temp. Range	Тѕтс	-40~+85	°C	

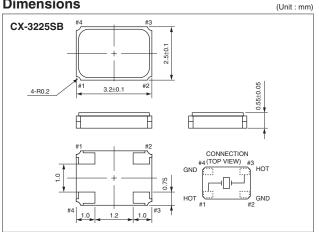
Table1 Motional Series Resistances

Frequency Range	Motional Series Resistance	Units
12000~13999kHz	300	
14000~15999kHz	200	- 1
16000~26999kHz	100	ohm
27000~54000kHz	50	

Table2 Level of Drive

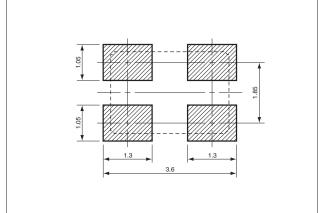
Frequency Range	Level of Drive	Units
12000~54000kHz	10(100 max.)	μW

Dimensions

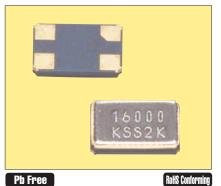


Recommended Land Pattern

(Unit : mm)







- Reference frequency for telecommunication systems
- Reflow compatible
- Using Ceramic Package resulting in high reliability
- Small and low profile

Applications

• Mobile communications, Bluetooth, Wireless LAN

Standard Frequencies (kHz)

12000.000	26000.000
13000.000	32000.000
16000.000	40000.000
20000.000	

^{*} Please inquire about frequencies other than the above.

Specifications

Items	Symbol	Specification	Units	Remarks
Frequency Range	Fo	12000~40000	kHz	
Overtone Order		Fundamental		
Frequency Tolerance	ΔF/F	±10	ppm	@ 25°C
Frequency Temperature Characteristics	ΔF/T	±15	ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	CI	Table 1	ohm	
Level of Drive		Table 2	μW	
Load Capacitance	C∟	10	pF	
Operating Temp. Range	Topr	-30~+85	°C	
Storage Temp. Range	Тѕтс	-40~+85	°C	

^{*} Please inqurie about specifications other than the above.

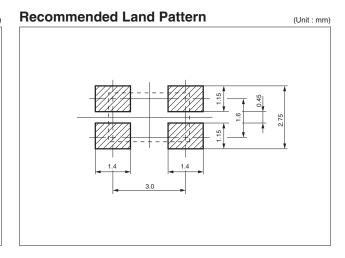
Table1 Motional Series Resistances

Frequency Range	Motional Series Resistance	Units
12000~1999kHz	80	
20000~40000kHz	50	ohm

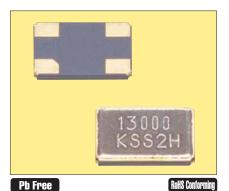
Table2 Level of Drive

Frequency Range	Level of Drive	Units
12000~40000kHz	10(100 max.)	μW

Dimensions (Unit: mm) CX-4025S







- Reference frequency for telecommunication systems
- Reflow compatible
- Using Ceramic Package resulting in high reliability
- Small and low profile

Applications

• Mobile communications, Bluetooth, Wireless LAN

Standard Frequencies (kHz)

12000.000	19200.000
12800.000	26000.000
13000.000	32000.000
14400.000	40000.000
16000.000	48000.000

^{*} Please inquire about frequencies other than the above.

Specifications

Items	Symbol	Specification		Units	Remarks
Frequency Range	Fo	9843.75~49999	50~120(MHz)	kHz	
Overtone Order		Fundamental	3rd Overtone		
Frequency Tolerance	ΔF/F	±10	±10		@ 25°C
Frequency Temperature Characteristics	ΔF/T	±15		ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	CI	Table 1		ohm	
Level of Drive		Table 2		μW	
Load Capacitance	C∟	10		pF	
Operating Temp. Range	Topr	-30~+85		°C	
Storage Temp. Range	Тѕтс	-40~+85		°C	

^{*} Please inqurie about specifications other than the above.

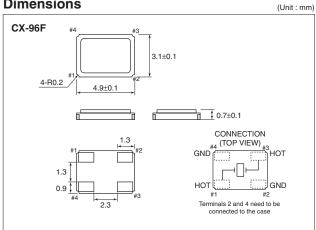
Table1 Motional Series Resistances

Frequency Range	Motional Series Resistance	Units
9843.75~9999kHz	150	
10000~11999kHz	80	
12000~25999kHz	50	ohm
26000~49999kHz	40	
50~120(MHz)	80	

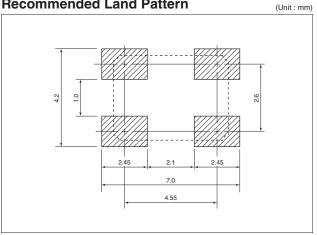
Table2 Level of Drive

Frequency Range	Level of Drive	Units
10000~49999kHz	10(100 max.)	
50~120(MHz)(3rdO.T)	10(100 max.)	μW

Dimensions

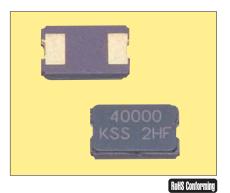


Recommended Land Pattern









- Crystal Unit for Audio-Visual, Office Equipment.
- Small and low profile.(5.0x3.2x1.1mm)
- Ceramic package.
- Product with lead free terminations.
- Reflow compatible.

Applications

- Digital electronics
- Audio visual, Office equipment

Standard Frequencies $_{(kHz)}$

10000.000	24000.000
12000.000	24545.450
14318.180	24576.000
14745.600	27000.000
16934.400	36000.000
18432.000	48000.000
22579.200	54000.000

^{*} Please inquire about frequencies other than the above.

Specifications

Items	Symbol	Specification	Units	Remarks
Frequency Range	Fo	9843.75~54000	kHz	
Overtone Order		Fundamental		
Frequency Tolerance	ΔF/F	±50	ppm	@ 25°C
Frequency Temperature Characteristics	ΔF/T	±50	ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	CI	Table 1	ohm	
Level of Drive		Table 2	μW	
Load Capacitance	C∟	12	pF	
Operating Temp. Range	Topr	-10~+70	°C	
Storage Temp. Range	Тѕтс	-40~+85	°C	

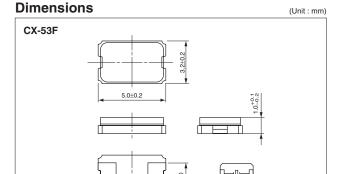
^{*} Please inqurie about specifications other than the above.

Table1 Motional Series Resistances

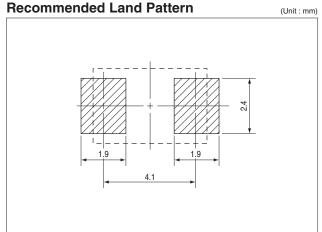
Frequency Range Motional Series Resistance		Units
9843.75~11999kHz	200	
12000~13999kHz	150	
14000~29999kHz	100	ohm
30000~54000kHz	50	

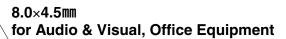
Table2 Level of Drive

Frequency Range	Level of Drive	Units
9843.75~15999kHz	10(500 max.)	
16000~24999kHz	10(300 max.)	μW
25000~54000kHz	10(100 max.)	



CONNECTION









- Crystal Unit for Audio-Visual, Office Equipment.
- Small and low profile.(8.0x4.5x1.8mm)
- Ceramic package.
- Product with lead free terminations.
- Reflow compatible.

Applications

• Audio visual, Office equipment

Standard From	(kHz)	
14318.180	20000.000	28636.360
16000.000	21477.270	30000.000
16384.000	24000.000	32000.000
16934.400	24576.000	36000.000
19660.800	27000.000	40000.000

^{*} Please inquire about frequencies other than the above.

Specifications

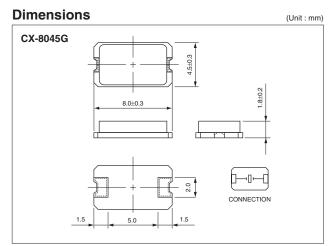
Items	Symbol	Specification	Units	Remarks
Frequency Range	Fo	7200~48000	kHz	
Overtone Order		Fundamental		
Frequency Tolerance	ΔF/F	±50	ppm	@ 25°C
Frequency Temperature Characteristics	ΔF/T	±50	ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	CI	Table 1	ohm	
Level of Drive		Table 2	μW	
Load Capacitance	C∟	12	pF	
Operating Temp. Range	Topr	-10~+70	°C	
Storage Temp. Range	Тѕтс	-40~+85	°C	

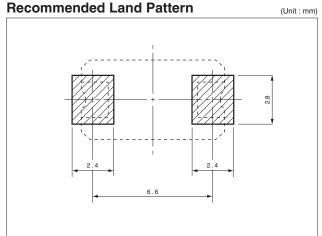
^{*} Please inqurie about specifications other than the above.

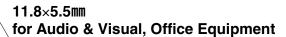
Table1 Motional Series Resistances

Frequency Range	Motional Series Resistance	Units
7200~9999kHz	200	
10000~11999kHz	150	ohm
12000~30000kHz	50	

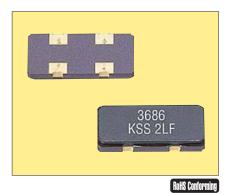
Frequency Range	Level of Drive	Units
7200~9999kHz 10(500 max.)		
16000~24999kHz	10(300 max.)	μW
25000~32000kHz	10(100 max.)	











- Crystal Unit for Automotive Electronics.
- Small and low profile.(11.8x5.5x1.8mm)
- Ceramic package.
- Product with lead free terminations.
- Reflow compatible.

Applications

- Digital electronics
- Audio & visual, Office equipment

Standard Frequencies (KHz)

	, ,
3579.545	14318.180
3686.400	16000.000
4000.000	16934.400
6000.000	19660.800
8000.000	20000.000
12000.000	

^{*} Please inquire about frequencies other than the above.

Specifications

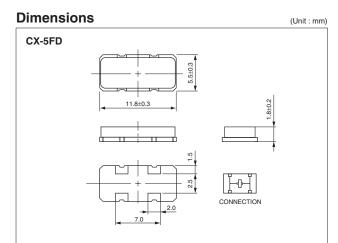
Items	Symbol	Specification		Units	Remarks
Frequency Range	Fo	3500~28999	29~60(MHz)	kHz	
Overtone Order		Fundamental	3rd. Overtone		
Frequency Tolerance	ΔF/F	±50	±50		@ 25°C
Frequency Temperature Characteristics	ΔF/T	±50		ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	CI	Table 1		ohm	
Level of Drive		Table 2		μW	
Load Capacitance	CL	12		pF	
Operating Temp. Range	Topr	−10~+70		°C	
Storage Temp. Range	Тѕтс	-40~+85		°C	

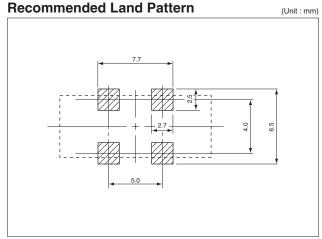
^{*} Please inqurie about specifications other than the above.

Table1 Motional Series Resistances

Frequency Range	Units	
3500~3999kHz	300	
4000~7999kHz	200	
8000~11999kHz	120	ohm
12000~20000kHz	100	
29~60MHz	150	

Frequency Range	Level of Drive	Units
3500∼15999kHz	10(500 max.)	
16000~28999kHz	10(300 max.)	μW
29~60MHz	10(300 max.)	











- Crystal Unit for Audio & Visual, Office Equipment.
- · Metal package, lead type.
- A resistance weld hermetic sealed type.
- Suitable for high density assembly and mass production.

Applications

- Digital electronics
- Audio & visual, Office equipment

Standard Fr	(kHz)	
3200.000	7200.000	14318.180
3579.545	7372.800	16000.000
3686.400	8000.000	16934.400
4000.000	10000.000	17280.000
4194.304	10240.000	17734.476
4332.000	10738.635	20000.000
4433.619	11000.000	21477.270
4500 000	11059 200	24000 000

12000.000

12288.000

13500.000

(MHz)

24576.000

25000.000

27000.000

29.491200	35.328000	50.000000
32.000000	40.000000	54.000000
33.868800	48.000000	60.000000

^{*} Please inquire about frequencies other than the above.

4915.200

6000.000

6144.000

Specifications

Items	Symbol	Specifi	ication	Units	Remarks
Frequency Range	Fo	3200~33999kHz	30~60 (MHz)	kHz	
Overtone Order		Fundamental	3rd Overtone		
Frequency Tolerance	ΔF/F	±50		ppm	@ 25°C
Frequency Temperature Characteristics	ΔF/T	±50		ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	CI	Table 1		ohm	
Level of Drive		Table 2		μW	
Load Capacitance	CL	12		pF	
Operating Temp. Range	Topr	−10~+70		°C	
Storage Temp. Range	Тѕтс	-40~+85		°C	

^{*} Please inqurie about specifications other than the above.

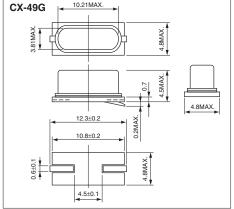
Table1 Motional Series Resistances

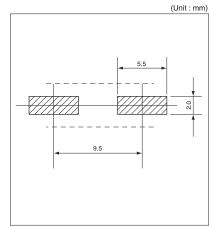
Frequency Range	Motional Series Resistance	Units
3200~3499kHz	300	
3500~4099kHz	150	
4100~4799kHz	120	
4800~5999kHz	100	ohm
6000~11999kHz	90	OIIII
12000~13499kHz	70	
13500~33999kHz	50	
30~60MHz	150	

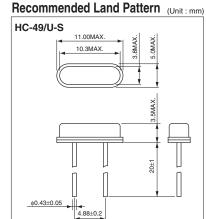
Table2 Level of Drive

Frequency Range	Level of Drive	Units
3200~15999kHz	10(500 max.)	
16000~24999kHz	10(300 max.)	
25000~33999kHz	10(100 max.)	μW
30~60MHz	10(300 max.)	

Dimensions











- Crystal Unit for Automotive Electronics.
- Small and low profile.(5.0x3.2x1.3mm)
- Ceramic package.
- Product with lead free terminations.
- Reflow compatible.

Applications

Engine control

Standard Frequencies (KHz)

	. ,
10000.000	18000.000
12000.000	20000.000
15000.000	24000.000
16000.000	25000.000

^{*} Please inquire about frequencies other than the above.

Specifications

Items	Symbol	Specification	Units	Remarks
Frequency Range	Fo	9843.75~40000	kHz	
Overtone Order		Fundamental		
Frequency Tolerance	ΔF/F	±100	ppm	@ 25°C
Frequency Temperature Characteristics	ΔF/T	±200	ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	CI	Table 1	ohm	
Level of Drive		Table 2	μW	
Load Capacitance	C∟	12	pF	
Operating Temp. Range	Topr	−40~+125	°C	
Storage Temp. Range	Тѕтс	−40~+150	°C	

^{*} Please inqurie about specifications other than the above.

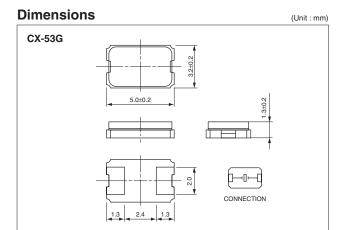
Table1 Motional Series Resistances

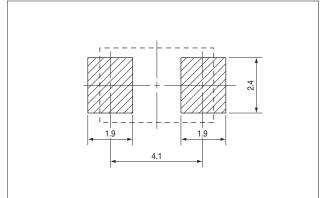
Frequency Range	Motional Series Resistance	Units
9843.75~11999kHz	200	
12000~13999kHz	150	- 1
14000~29999kHz	100	ohm
30000~40000kHz	50	

Table2 Level of Drive

Recommended Land Pattern

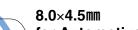
Frequency Range	Level of Drive	Units
9843.75~15999kHz	10(500 max.)	
16000~24999kHz	10(300 max.)	μW
25000~40000kHz	10(100 max.)	





(Unit : mm)







- Crystal Unit for Automotive Electronics.
- Small and low profile.(8.0x4.5x1.9mm)
- Ceramic package, J lead type.
- Product with lead free terminations.
- Reflow compatible.

Applications

• Engine control, TPMS

Standard Frequencies (kHz)

8000.000	16000.000		
9843.750	18000.000		
10000.000	20000.000		
12000.000	24000.000		
13560.000	25000.000		
14000.000	30000.000		

^{*} Please inquire about frequencies other than the above.

Specifications

▼KYOCERa

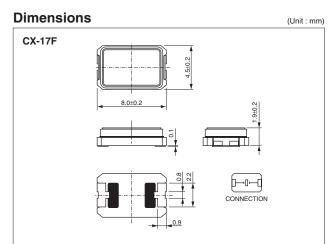
Items	Symbol	Specification	Units	Remarks
Frequency Range	Fo	8000~30000	kHz	
Overtone Order		Fundamental		
Frequency Tolerance	ΔF/F	±100	ppm	@ 25°C
Frequency Temperature Characteristics	ΔF/T	±200	ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	CI	Table 1	ohm	
Level of Drive		Table 2	μW	
Load Capacitance	CL	12	pF	
Operating Temp. Range	Topr	-40~+125	°C	
Storage Temp. Range	Тѕтс	-40~+150	°C	

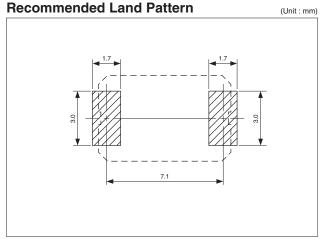
^{*} Please inqurie about specifications other than the above.

Table1 Motional Series Resistances

Frequency Range	Motional Series Resistance	Units
8000~9999kHz	200	
10000~11999kHz	150	ohm
12000~30000kHz	100	

Frequency Range	cy Range Level of Drive	
8000~15999kHz	10(500 max.)	
16000~24999kHz	10(300 max.)	μW
25000~30000kHz	10(100 max.)	











- Crystal Unit for Automotive Electronics.
- Small and low profile.(11.8x5.5x2.5mm)
- Ceramic package.
- Product with lead free terminations.
- Reflow compatible.

Applications

Engine control

Standard Frequencies (KHz)

	, ,
4000.000	12000.000
5000.000	16000.000
6000.000	18000.000
8000.000	20000.000
10000.000	

^{*} Please inquire about frequencies other than the above.

Specifications

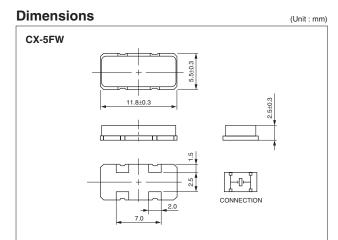
Items	Symbol	Specification	Units	Remarks
Frequency Range	Fo	3500~20000	kHz	
Overtone Order		Fundamental		
Frequency Tolerance	ΔF/F	±100	ppm	@ 25°C
Frequency Temperature Characteristics	ΔF/T	±200	ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	CI	Table 1	ohm	
Level of Drive		Table 2	μW	
Load Capacitance	CL	12	pF	
Operating Temp. Range	Topr	-40~+125	°C	
Storage Temp. Range	Тѕтс	-40~+125	°C	

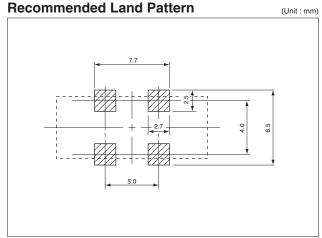
^{*} Please inqurie about specifications other than the above.

Table1 Motional Series Resistances

Frequency Range Motional Series Resistance		Units
3500~3999kHz	300	
4000~7999kHz	200	ohm
8000~11999kHz	120	Ollili
12000~20000kHz	100	

Frequency Range	Level of Drive	Units	
3500~15999kHz	10(500 max.)	\^/	
16000~20000kHz	10(300 max.)	μW	









- Crystal Unit for Automotive Electronics.
- Metal package, lead type.
- A resistance weld hermetic sealed type.
- Suitable for high density assembly and mass production.

Applications

• Engine control

Standard Frequencies (kHz)

	. ,
4000.000	12000.000
5000.000	16000.000
6000.000	18000.000
8000.000	20000.000
10000.000	

^{*} Please inquire about frequencies other than the above.

Specifications

Items	Symbol	Specification	Units	Remarks
Frequency Range	Fo	3200~20000	kHz	
Overtone Order		Fundamental		
Frequency Tolerance	ΔF/F	±100	ppm	@ 25°C
Frequency Temperature Characteristics	ΔF/T	±200	ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	CI	Table 1	ohm	
Level of Drive		Table 2	μW	
Load Capacitance	CL	12	pF	
Operating Temp. Range	Topr	-40~+125	°C	
Storage Temp. Range	Тѕтс	-40~+125	°C	

^{*} Please inqurie about specifications other than the above.

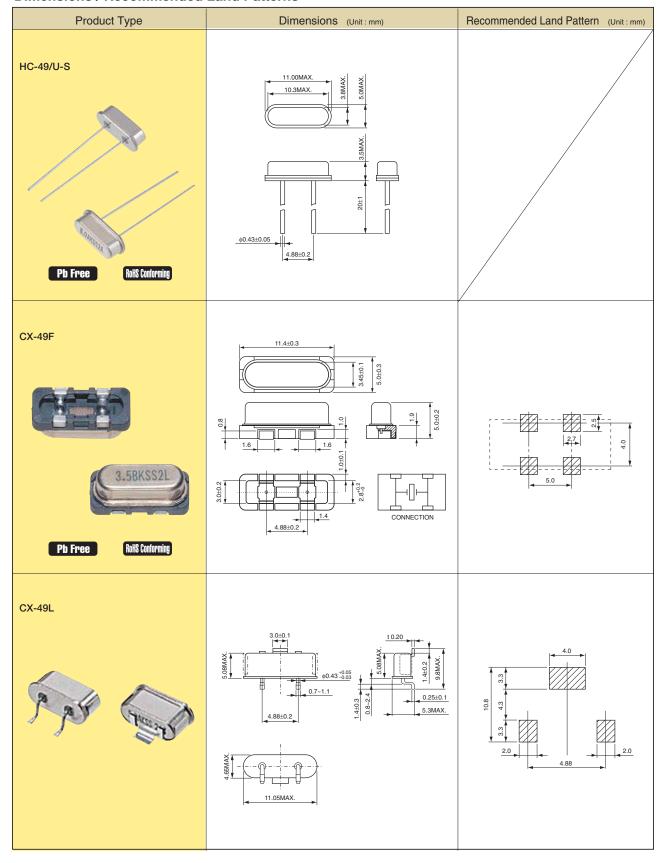
Table1 Motional Series Resistances

Frequency Range	Motional Series Resistance	Units
3200~3499kHz	300	
3500~4099kHz	150	
4100~4799kHz	120	
4800~5999kHz	100	ohm
6000~11999kHz	90	
12000~13499kHz	70	
13500~20000kHz	50	

Frequency Range	Level of Drive	Units
3200~15999kHz	10(500 max.)	. 147
16000~20000kHz	10(300 max.)	μW



Dimensions / Recommended Land Patterns





1. Shock & Drop • Vibration

Do not inflict excessive shock and mechanical vibration that exceeds the norm, such as hitting or mistakenly dropping, when transporting and mounting on a board. There are cases when pieces of crystal break, and pieces that are used become damaged, and become inoperable. When a shock or vibration that exceeds the norm has been inflicted, make sure to check the characteristics.

2. Cleaning

Since a crystal piece can be broken by resonance when a crystal device is cleaned by ultrasonic cleaning. Be careful when carrying out ultrasonic cleaning.

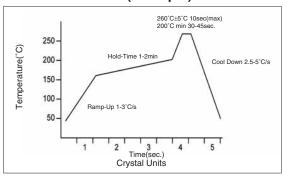
3. Soldering conditions

To maintain the product reliability, please follow recommended conditions.

Standard soldering iron conditions

	Crystal Units
Soldering iron	280°C ~ 340°C
Time	3+1/-0sec. max

Reflow conditions (Example)



Recommended reflow Conditions vary depending upon products. Please check with the respective specification for details.

4. Mounting Precautions

Leaded Devices

The special glass, located where the lead of the retainer base comes out, is aligned with the coefficient of thermal expansion of the lead, If the glass is damaged and cracks appear, there may be cases in which performance deteriorates and it fails to operate.

Consequently, when making the device adhere closely and applying solder, align the gap of the hole of the board with the gap of the lead and insert without excessive force.

When making the device adhere closely to a through hole board and applying solder, be careful that the solder does not get into the metal part of the retainer base and cause a short. Putting in an insulation spacer is one more method of preventing a short circuit.

When the lead is mounted floating, fix it as far as possible so that contact with other parts and the breakage due to the fatigue, and the mechanical resonance of the lead will not occur.

When the lead is bent and used, do not bend the lead directly from the base, separate it 0.5mm or more and then bend it. When bending, before attaching to the board, fix the place where the lead comes out in advance and attach it after bending so that a crack does not occur in the glass part.

Surface Mount Devices

The lead of the device and the pattern of the board is soldered on the surface. Since extreme deformation of the board tears off the pattern, tears off the lead metal, cracks the solder and damages the sealed part of the device and there are cases in which performance deteriorates and operation fails, use it within the stipulated bending conditions. Due to the small cracks in the board resulting from mounting, please pay sufficient attention when attaching a device at the position where the warping of the board is great.

When using an automatic loading machine, as far as possible, select a type that has a small impact and use it while confirming that there is no

Surface mount devices are NOT flow soldering compatible.

5. Storage Condition

Since the long hour high temperature and low temperature storage, as well as the storage at high humidity are causes of deterioration in frequency accuracy and solderability.

Parts should be stored in temperature range of -5 to +40C°, humidity 40 to 60% RH, and avoid direct sunlight. Then use within 6 months.





For Proper Use of Crystal Units

1. Characteristics of crystal units

The thickness of crystal vibrator of the AT cut crystal unit as described in the previous page differs depending on the overtone mode.

(1) Relationship between thickness of crystal blank and oscillation frequency

Cut angle/mode overtone	Frequency range (MHz)	Formula of thickness of crystal blank
AT/Fundamental mode	3.5~ 33	1.67/f
AT/3'rd O. T	33~100	5.01/f
AT/5'th O. T	100~150	8.35/f
AT/7'th O. T	150~200	11.69/f

f : Series resonance frequency. (MHz)

In case of calculating the thickness of AT-cut 16MHz t=1.67/16=0.104(mm)

(2) Examples of specifications for frequency-temperature characteristics

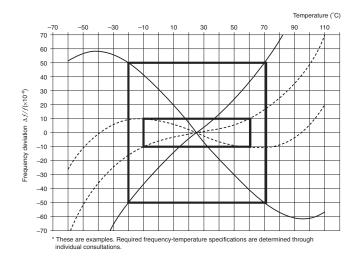
The frequency-temperature characteristics of the AT cut crystal unit are tertiary curves.

The diagram below shows examples of the tertiary curves that pass temperature range and frequency deviation specifications.

The range enclosed by the smaller rectangular satisfies the following specification:

±10×10-6 (-10 to 60: 25°C)

The range enclosed by the larger rectangular satisfies the following specification: $\pm 50 \times 10^{-6}$ (-20 to 70: 25°C)



(3) Equivalent electric circuit and equivalent constant of crystal unit

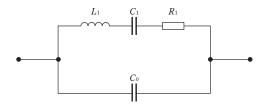
The following equivalent constants are used near the resonance frequency.

 L_1 : Motional inductance in the equivalent electric circuit

C1: Motional capacitance in the equivalent electric circuit

 ${\it R}$: Motional resistance in the equivalent electric circuit

Co: Parallel capacitance in the equivalent electric circuit



Equivalent electric circuit of a quarts crystal unit





(4) Items calculated by equivalent constants and load capacitance

$$f_{\rm s}$$
: Series resonance frequency
$$f_{\rm s} = \frac{1}{2\pi \sqrt{L1 \cdot C1}}$$

$$f_{\rm p}$$
: Parallel resonance frequency
$$f_{\rm p} = \frac{1}{2\pi \sqrt{L_1 \frac{C_0 \cdot C_1}{C_0 + C_1}}}$$

$$\gamma$$
 : Capacitance ratio
$$\gamma = \frac{C_0}{C_1}$$

$$f_{\rm L}$$
 : Load resonance frequency
$$f_{\rm L} = f_{\rm s} \left(\frac{C_1}{2 \cdot (C_0 + C_{\rm L})} + 1 \right)$$

$$R_{\rm L}$$
 : Load resistance $R_{\rm L}$ = $R_{\rm l} \left(1 + \frac{C_0}{C_{\rm L}}\right)^2$

$$C_{\rm L}$$
: Load capacitance $C_{\rm L} = \frac{C_1}{2} \cdot \frac{1}{(f_1/f_2)-1} - C_0$

$$Q$$
 : Quality factor
$$Q = \frac{2\pi \cdot f_{\rm s} \cdot L_1}{R_1} = \frac{1}{2\pi \cdot f_{\rm s} \cdot C_1 \cdot R_1}$$

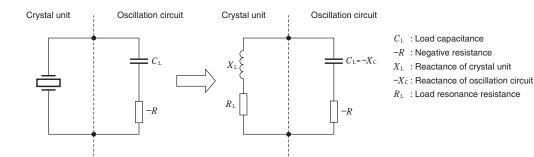
The equation f_L shows that f_L varies as load capacitance C_L connected to the crystal unit changes and that f_L becomes larger. as C_L becomes smaller.

The equation R_L shows the change in impedance with a load capacitance connected. The impedance of crystal unit becomes larger as C_L becomes smaller.

2. Oscillation circuit and crystal unit

(1) Equivalent circuit of oscillation circuit and oscillation conditions

A simplified equivalent circuit is shown below.





The oscillation start-up conditions are described as

$$R_{\rm L} \ge |-R|$$

, and in order to oscillate the crystal unit accurately, it must be designed such that the negative resistance of the oscillation circuit becomes bigger comparing with the resonance resistance value at the time of loading. This ratio is called oscillation margin degree $M_{\rm OSC}$ and it is one of critical factors when designing the oscillation circuit and is described as below.

For oscillation circuit designing conditions, it is recommended that an oscillation circuit be designed using a negative resistance of a value five to ten times or more larger than RL calculated from the resonance resistance specification value.

$$M_{\rm OSC} = |-R|/R_{\rm L} \ge 5$$

In a steady oscillation state, the load resonance resistance is given as follows:

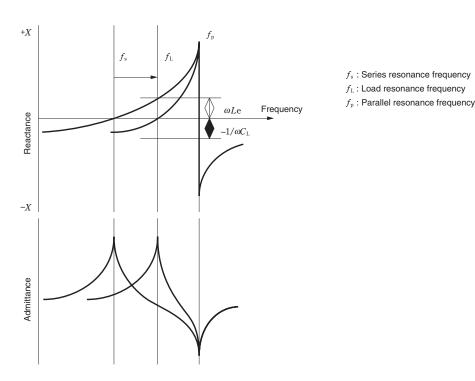
$$R_{\rm L} = |-R|$$

The mutual conductance of the oscillation circuit decreases after the oscillation has started to continuously compensate for the power loss due to the load resonance resistance of the crystal unit, which continues oscillation.

The frequency condition is given as follows:

$$X_{\rm L} = X_{\rm C}, X_{\rm L} - X_{\rm C} = 0$$

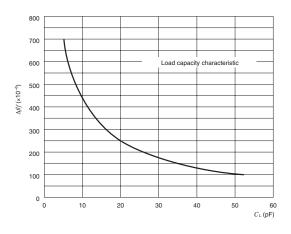
As shown in the following figure, the reactance of the crystal unit varies to a value matching the load capacitance of the oscillation circuit $C_L = X_C$. Thus an oscillation frequency is determined.





(2) Changes of load capacitance and oscillation frequency

As shown above, the series resonance frequency of the crystal unit changes with load capacitance $C_{\rm L}$ of the oscillation circuit. In the actual oscillation circuit, however, fine adjustments of oscillation frequencies are carried out by varying $C_{\rm L}$ by the trimmer capacitor or the like. The following figure shows an example of load capacitance characteristics. The slope of the characteristics varies depending on the frequency, shape, the number of overtone mode, etc.

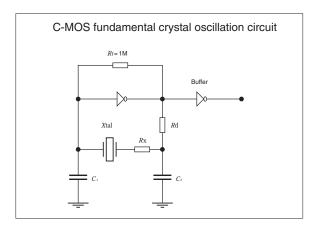


3. Crystal oscillation circuit

(1) C-MOS fundamental crystal oscillation circuit

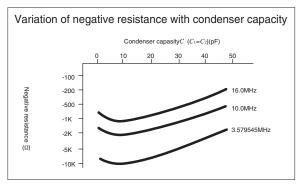
As shown above, the series resonance frequency of the crystal The figure on the right shows a standard C-MOS inverter crystal oscillation circuit for oscillating crystal unit with fundamental mode.

 * Rx is an element to reduce excitation current of the crystal unit preventing frequency fluctuation, but Rx is not used in some cases.

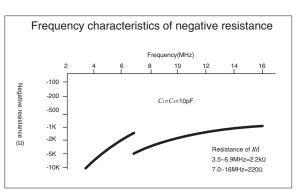


Characteristics of the circuit when load capacitances C_1 and C_2 are changed under the condition of $C_1 = C_2$ are shown in the figure on the right.

It is not desirable that the excessive increase of the value of condenser leads to a decrease of the negative resistance resulting in increasing the possibility of oscillation failure.



Rd mainly adjusts frequency characteristics of the negative resistance and is used to prevent oscillating by third Overtone mode. In case of a bigger circuit of the negative resistance, there is a case it is used to prevent the abnormal oscillation.





Selection	of ICs and	d circuit constar	nte hv freauei	nev hands

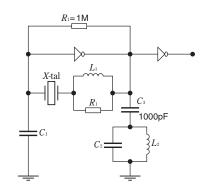
Frequency		3~4.9(MHz)	5~6.9(MHz)	7~9.9(MHz)	10~19.9(MHz)	20~30(MHz)	
IC			TC4069UB TC4SU69F		TC74HCU04A TC7SU04F TC7WU04FU	TC74VHCU04 TC7SHU04F TC7WHU04FU	
Rf		1M					
Rd	*1	1500()	470()	0()	0()	0()	
Rx	*2	0~1500					
C_1, C_2	*3	6~22(pF) 6~15(pF) 6~15(pF)			6~15(pF)		

 $^{^{\}star}$ 1: Necessary for preventing overtone oscillation and must be changed depending on the frequency band or the C_1 and C_2 values.

(2) C-MOS overtone crystal oscillation circuit

This figure shows a standard C-MOS inverter crystal oscillation circuit to oscillate a crystal unit using the overtone mode.

C-MOS overtone crystal oscillation circuit



There are same cases when L_1 and R_1 are matched to the value of load capacitance.

(3) Selection of ICs and circuit constants by frequency bands

Frequency range	20~60(MHz)		
IC	TC74VHCU04 TC7SHU04F TC7WHU04FU		
C_1	3~10pF		
C_2	10~22pF		

(4) Method of selecting circuit constants and functions of elements

- C_1 : Forms load capacitance of the circuit together with C_2 , L_1 and L_2 . A value of approx. 5pF is used.
- C_2 : Forms load capacitance of the circuit together with C_1 , L_1 and L_2 . Prevents fundamental wave oscillation. Shall be selected so that C_2 comes between the third overtone frequency at which resonance frequency with L_2 is to make oscillation and 1/3 of the third overtone frequency. A value of 10 to 22pF is used.
- C₃: A bypath capacitor
- L1: A coil to adjust load capacitance of the oscillation circuit to a value near the series. A value of several µH is used.
- L_2 : Forms load capacitance of the circuit together with C_1 , C_2 and L1. Prevents fundamental wave oscillation. Shall be selected so that L2 comes between the third overtone frequency at which resonance frequency with C_2 is to make oscillation and 1/3 of the third overtone frequency. A value of 10 to 22pF is used.
- R_1 : A Q dump resistor for L_1 . As an element for preventing self-excited oscillation, A value of several $k\Omega$ to several tens of $k\Omega$ is used.



^{*2:} Used to reduce excitation current of the crystal unit. Necessary for stable operation of small-sized crystal units.

^{*3:} The optimum value differs with the values of load capacitance and Rd.

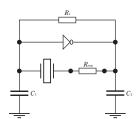
^{*} L_1 and R_1 might not be used.



(5) Method of checking oscillation circuit

qSome ICs have a low upper-limit value of usable frequency, so refer to individual IC catalog to make sure that the IC can oscillate a crystal unit with an adequate negative resistance.

wThe following figure shows an example of a C-MOS oscillation circuit. Check resistance Rsup is connected in series with the crystal unit to check the negative resistance. Use 3 to 22pF for C_1 and C_2 , and see the table below for values of check resistance.



Frequency range	Values of check resistance				
3.5~4.5MHz	1.5k				
4.6~6.0MHz	1.0k				
6.1~10.0MHz	800				
10.1~14.0MHz	500				
14.1~20.0MHz	400				

eUsing a spectrum analyzer or oscilloscope, check that every oscillation is normally activated while turning the power on and off several times. For oscillation circuits with no power regulator ICs, carefully check changes in the negative resistance against supply voltage and in frequencies.

nd Mhen oscillation is normal, remove the check resistance before using the crystal circuit.

th oscillation is unstable or is not generated, gradually decrease the values of C_1 and C_2 until normal oscillation is obtained.

ylf normal oscillation cannot be generated near 10MHz or near 20MHz, replace the IC with a new one suitable for higher frequencies.

(6) Load capacitance and oscillation frequency of transistor/fundamental crystal oscillation circuit

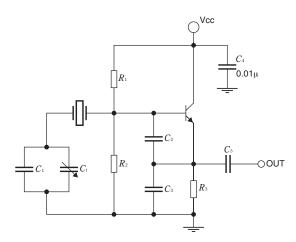
Viewed from the connection terminals of a crystal unit, the load capacitance C_L of an oscillation circuit is generally comprised of C_1 , C_t , C_2 , and C_3 if stray capacitance of the circuit and the capacitance between base and emitter of the transistor are ignored. Since trimmer capacitor is adjusted to $C_T = MIN$. to MAX. for zero adjustment of the oscillation frequency, the value of C_L at this time can be obtained from the following equation.

$$C_{L}$$
MIN. = $\left(\frac{1}{C_{1} + C_{T}} + \frac{1}{C_{2}} + \frac{1}{C_{3}}\right)^{-1} \sim C_{L}$ MAX. = $\left(\frac{1}{C_{1} + C_{T}} + \frac{1}{C_{2}} + \frac{1}{C_{3}}\right)^{-1}$

When these calculation results are substituted for the following equation for load resonance frequency, the oscillation frequency can be obtained.

$$f_{\rm L} = f_{\rm s} \left(\frac{C_1}{2 \cdot (C_0 + C_{\rm L})} + 1 \right)$$





Select each circuit constant so that the adjustment ranges of upper and lower frequencies of this circuit are even on the basis of the frequency of a single crystal unit measured using a specified load capacity, and that the margin of ± 8 to 10×10^{-6} of the room temperature deviation of the crystal unit can be reserved.

To prevent the decrease in the negative resistance, always connect the crystal unit to the base of the transistor. For transistors used for oscillation circuits, he and fT are important.

To obtain the large negative resistance with small current consumption, select a transistor for high frequency amplification with high of over 250 and f_T of 1GHz or more.

(7) Transistor third overtone oscillation circuit

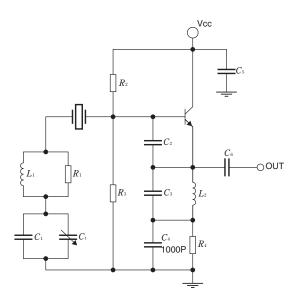
qThe resonance circuit comprised of L_2 and C_3 is required on the emitter side for preventing fundamental mode crystal oscillation. Set the resonance frequency to a value higher than the intermediate between fundamental wave frequency and third overtone frequency.

w Use L_1 , referred to as an elongation coil, to connect the load capacitance of the oscillation circuit in series. R_1 prevents self-excited oscillation by L_1 . Since it is difficult in general to design the oscillation circuit having adequate negative resistance in the overtone oscillation frequency band, there are no other effective means of obtaining adequate oscillation margin except for preventing the increase of load resonance resistance R_L of the crystal unit.



 $R_{\rm L}$ in the equation of load resonance resistance can be made equal to $R_{\rm S}$ by connecting $C_{\rm L}$ in series, or making it infinite, which prevents increase in the load resonance resistance.

$$R_{\rm L} = R_1 \left(1 + \frac{C_0}{C_{\rm L}} \right)^2$$



To prevent decrease in the negative resistance, connect the crystal unit to the base of the transistor as in the fundamental mode crystal oscillation circuit. To use the crystal circuit for both oscillation and multiplication, connect a parallel resonance circuit having multiplication frequency as resonance frequency to the collector of the transistor.

When selecting circuit constants for zero adjustment range by trimmer capacitor, set the constants to values obtained by adding approx. ± 12 to 15×10^{-6} to the room temperature deviation of the crystal unit, centering the value obtained by measuring the crystal unit with load capacitances in series. (When the room temperature deviation specification of the crystal unit is $\pm 10 \times 10^{-6}$)

(8) Excitation power of oscillation circuit

Normal operation of crystal units is not assured when excitation power is raised. The allowable excitation power varies depending on the shape of the crystal unit or the stability of targeted frequency. When highly accurate oscillation is required, however, it is recommended to use an oscillation circuit with an excitation power of 5 to 50 μ W or less. For other cases, refer to individual relevant crystal units on the pages of the catalog.

(9) Precautions for designing printed circuit board

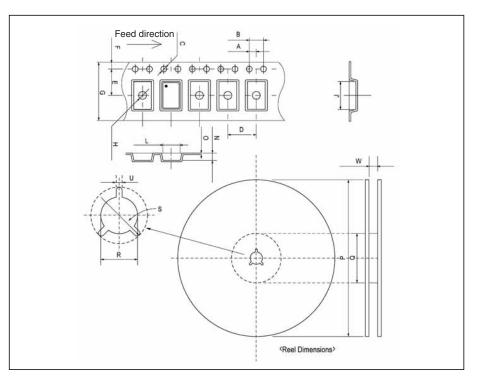
Be sure to design printed circuit board patterns that connect a crystal unit with other oscillation elements so that the lengths of such patterns become shortest possible to prevent deterioration of characteristics due to stray capacitances and wiring inductance. For multi-layer circuit boards, it is important not to wire the ground and other signal patterns right beneath the oscillation circuit.



Tape & Reel Specifications

■Crystal Units

		CX-2520SB	CX-3225SB (CX-101F)		
	Α	2.0±0.05	2.0±0.05		
	В	4.0±0.1	4.0±0.1		
	С	φ1.55±0.05	φ1.55±0.05		
	D	4.0±0.05	4.0±0.05		
_	Е	3.5±0.05	3.5±0.05		
T A P E	F	1.75±0.1	1.75±0.1		
P	G	8.0±0.2	8.0±0.2		
_	Н	φ1.05±0.1	φ1.05±0.1		
	J	3.5±0.1	3.5±0.1		
	L	2.8±0.1	2.8±0.1		
	N	0.85±0.1	0.85±0.1		
	0	0.25±0.05	0.25±0.05		
	Р	ф180+0/-3	φ180+0/-3		
R	Q	ф60+1/-0	φ60+1/-0		
E	R	φ13±0.2	φ13±0.2		
E	S	φ21±0.8	ф21±0.8		
	U	2.0±0.5	2.0±0.5		
	W	9±1	9±1		
Qty		3000/1000	3000/1000		



		KSX-23	CX-4025S	KSX-35 CX-96F	CX-53F CX-53G	CX-8045G CX-17F	KSX-36	CX-49F	CX-5FW CX-5FD	CX-49L
	Α	2.0±0.1	2.0±0.1	2.0±0.1	2.0±0.1	2.0±0.1	2.0±0.1	2.0±0.1	2.0±0.1	2.0±0.1
	В	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1
	С	φ1.5+0.1/-0	φ1.55±0.05	φ1.5±0.1	φ1.55±0.1	φ1.5±0.1	φ1.5±0.1	φ1.55±0.05	φ1.55±0.05	φ1.5±0.1
	D	4.0±0.1	4.0±0.1	8.0±0.1	8.0±0.1	8.0±0.1	8.0±0.1	8.0±0.1	12.0±0.1	16.0±0.1
_	Е	5.5±0.1	5.5±0.1	5.5±0.1	5.5±0.1	7.5±0.1	7.5±0.1	11.5±0.1	11.5±0.1	11.5±0.1
A	F	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1
P E	G	12.0±0.3	12.0±0.3	12.0±0.3	12.0±0.2	16.0±0.3	16.0±0.3	24.0±0.3	24.0±0.3	24.0±0.3
_	Н	φ1.5+0.1/-0	φ1.05±0.1	φ1.5±0.1	φ1.55±0.1	φ1.55±0.05	φ1.6±0.1	φ2.05±0.05	ф2.05±0.05	ф2.2±0.1
	J	3.5±0.1	4.2±0.1	5.5±0.1	5.4±0.1	8.4±0.1	6.5±0.1	11.5±0.1	12.2±0.1	
	L	2.8±0.1	2.7±0.1	3.7±0.1	3.6±0.1	4.9±0.1	4.2±0.1	5.4±0.1	5.85±0.1	
	N	1.0±0.1	0.95±0.05	1.4±0.1	1.7±0.1	2.1±0.1	1.5±0.1	5.5±0.1	2.8±0.1	6.5±0.1
	0	0.3±0.05	0.2±0.05	0.3±0.05	0.25±0.05	0.3±0.05	0.2±0.05	0.3±0.05	0.3±0.05	0.5±0.05
R E E	Р	ф330±2	φ180+0/-3	\$330±2\$178±2	φ330±2/φ254±2	φ330±2/φ254±2	\$330±2/\$178±2	ф330±2	ф330±2	ф330±2
	Q	φ100±1	ф60+1/-0	φ80±2φ100±1	φ100±1	φ80±1	φ80±2	φ100±1	φ100±1	φ100±1
	R	φ13±0.2	φ13±0.2	φ13±0.2	φ13±0.2	φ13±0.2	φ13±0.2	φ13±0.5	φ13±0.5	φ13±0.5
	S	ф21±0.8	φ21±0.8	ф21±0.8	φ21±0.8	φ21±0.8	φ21±0.8	ф21±0.5	φ21±0.5	
	U	2.0±0.5	2.0±0.5	2.0±0.5	2.0±0.5	2.0±0.5	2.0±0.5	2.0±0.2	2.0±0.5	
	W	13.5±0.5	13±1	13.5+1/-0.5	13.4+2/-0	16.0+2/-0	17.5+2/-0	25.5±0.5	24.4+2/-0	25.5+1/-0.5
C	Qty	5000/3000	3000/1000	5000/1000	3000/1000	3000/1000	5000/1000	1000	1000	5000



ORDERING FORMAT FOR CRYSTAL UNITS

Please specify the following items when ordering crystal units.

1. Type		
2. Nominal Frequency	Hz	
3. Overtone order		
4. Frequency Tolerance		×10 ⁻⁶ MAX. (at 25°C)
5. Frequency Stability vs. Tempera	ature Range (referred	to 25°C)
	×10 ⁻⁶ MAX,	°C ~°C
6. Motional Resistance		Ω MAX.
7. Load Capacitance(C∟)		pF
8. Drive Level		mW
9. Shunt Capacitance(C₀)		pF Max.
10. Others		
11. Marking		
12. Application		